



## DE2707500L

### Silicon epitaxial planar type

For ESD protection

DE2S075 in SSSMini2 type package

#### ■ Features

- High ESD
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

#### ■ Marking Symbol: EC

#### ■ Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

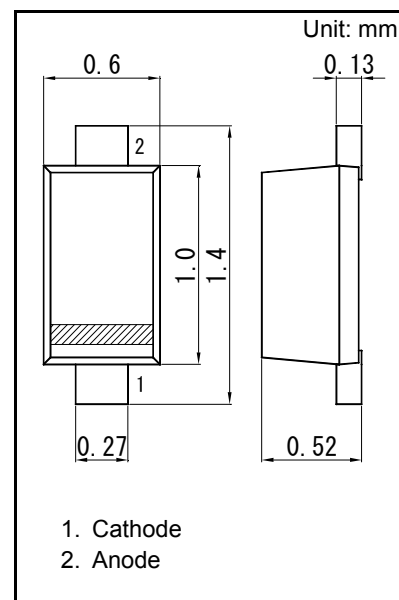
#### ■ Absolute Maximum Ratings Ta = 25 °C

| Parameter                             | Symbol | Rating      | Unit |
|---------------------------------------|--------|-------------|------|
| Total power dissipation <sup>*1</sup> | PT     | 120         | mW   |
| Electrostatic discharge <sup>*2</sup> | ESD    | ±30         | kV   |
| Junction temperature                  | Tj     | 150         | °C   |
| Operating ambient temperature         | Topr   | -40 to +85  | °C   |
| Storage temperature                   | Tstg   | -55 to +150 | °C   |

Note) <sup>\*1</sup>: Mounted on glass epoxy print board. ( 45 mm x 45 mm x 1 mm)

Solder in ( 0.4 mm x 0.3 mm)

<sup>\*2</sup>: Test method: IEC61000\_4\_2(C = 150 pF, R = 330 Ω, Contact discharge: 10 times)



|           |               |
|-----------|---------------|
| Panasonic | SSSMini2-F4-B |
| JEITA     | SC-104A       |
| Code      | SOD-723       |

#### Internal Connection



#### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

| Parameter                                              | Symbol | Conditions         | Min  | Typ | Max  | Unit  |
|--------------------------------------------------------|--------|--------------------|------|-----|------|-------|
| Zener voltage <sup>*1,*2</sup>                         | VZ     | IZ = 1 mA          | 7.13 |     | 7.88 | V     |
| Reverse current                                        | IR     | VR = 5 V           |      |     | 0.5  | μA    |
| Terminal capacitance                                   | Ct     | VR = 0V, f = 1 MHz |      | 47  |      | pF    |
| Temperature coefficient of zener voltage <sup>*3</sup> | SZ     | IZ = 1 mA          |      | 3.7 |      | mV/°C |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

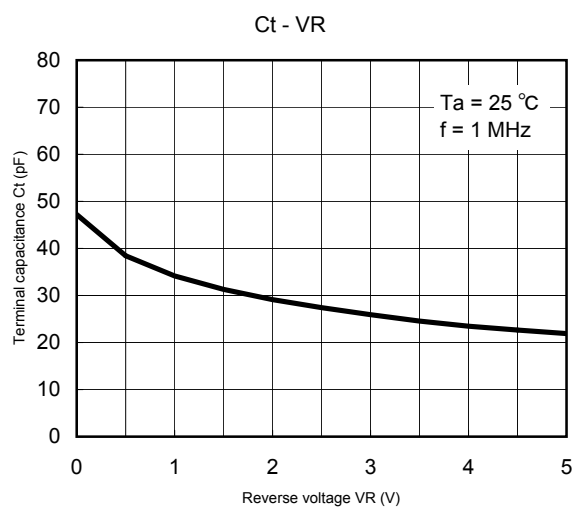
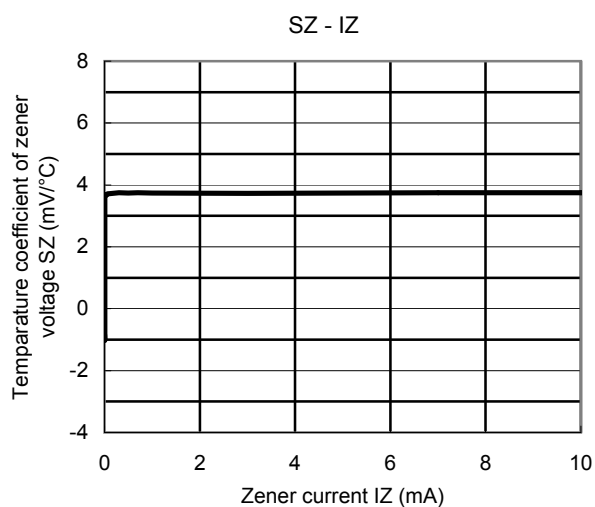
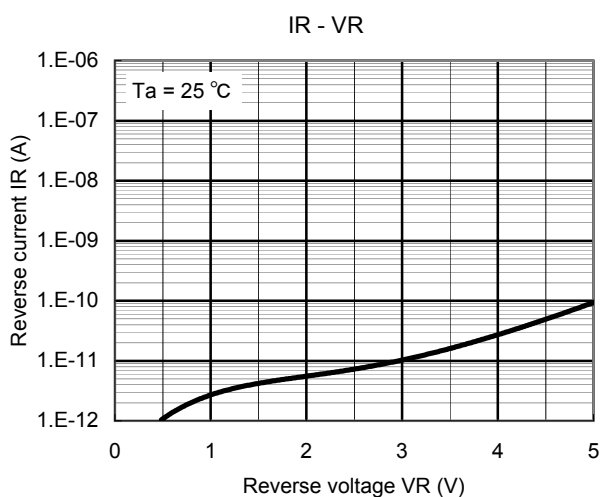
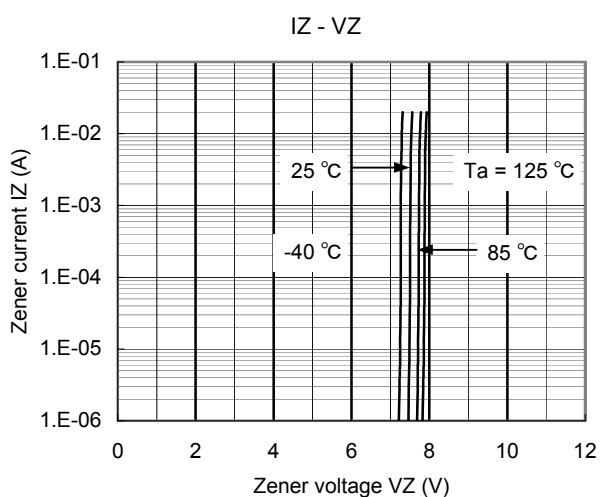
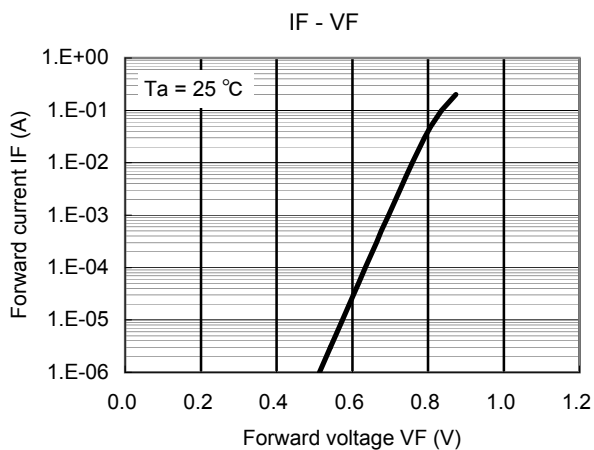
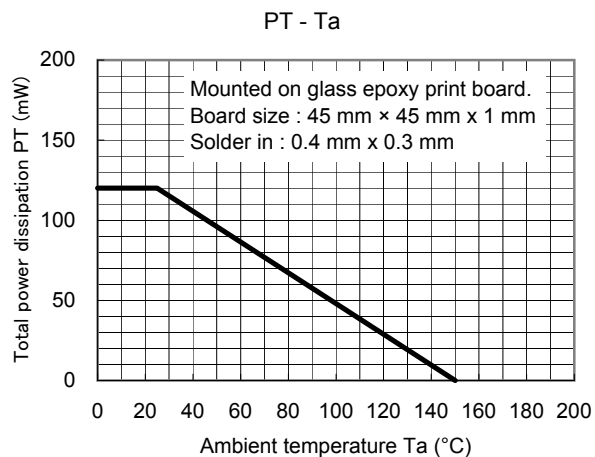
2. <sup>\*1</sup>: The temperature must be controlled 25°C for VZ measurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

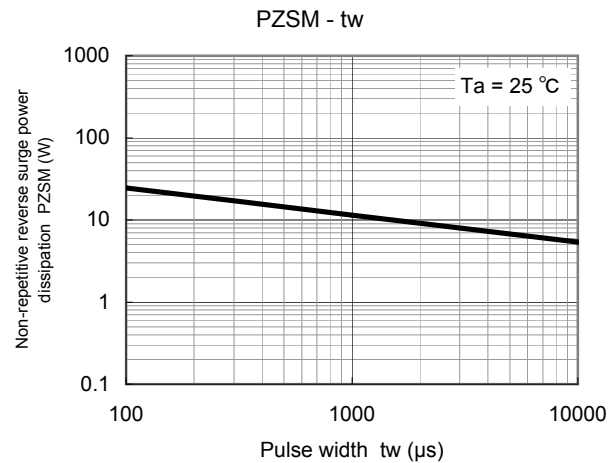
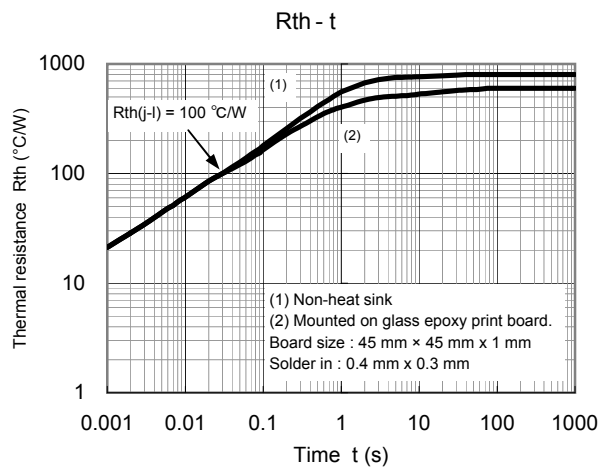
<sup>\*2</sup>: VZ guaranteed 20 ms after current flow.

<sup>\*3</sup>: Tj = 25°C to 150°C

Technical Data ( reference )

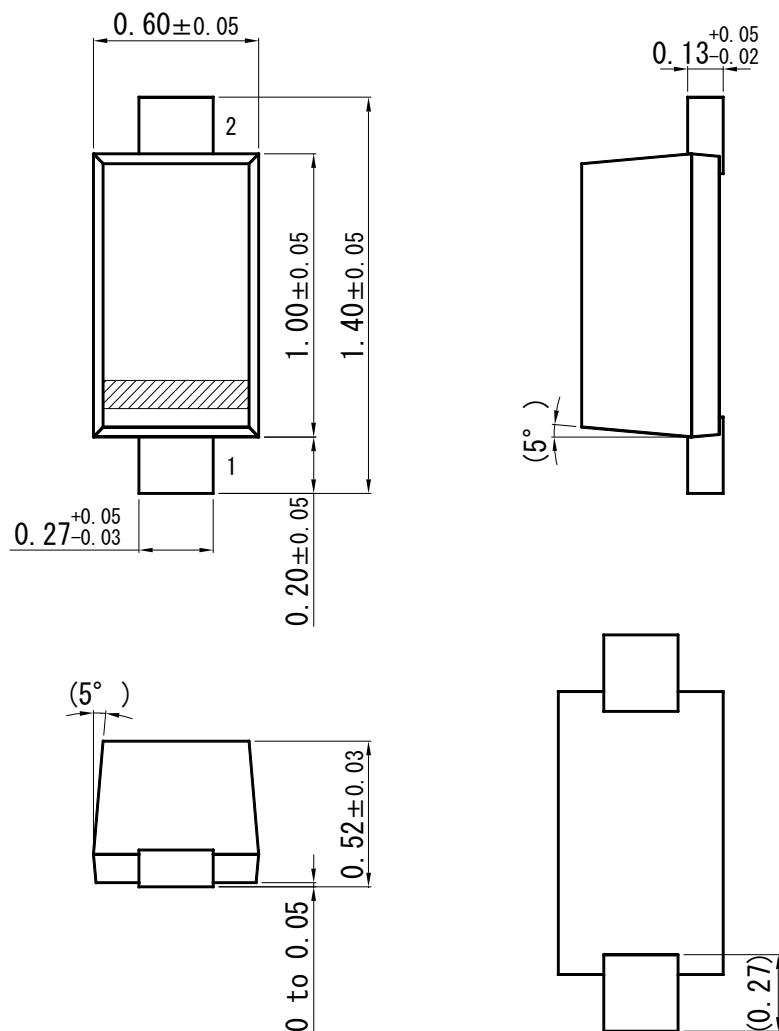


Technical Data ( reference )

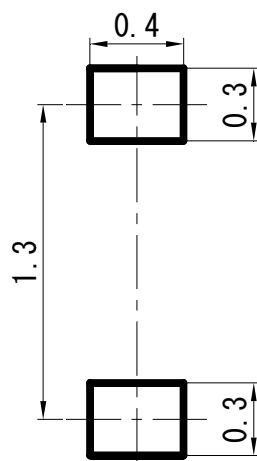


SSSMini2-F4-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)



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